

Application No.: 10/683,829
Docket No.: UC0343USCIP

Page 4

Remarks

The following remarks are responsive to the Office Action, dated September 27, 2005, in the above referenced pending application. Applicant respectfully requests reconsideration in view of the below remarks and withdrawal of the rejections.

Status of the Claims

Claims 1, 2, 4-10 and 12-16 are pending.

Claim 1 has been amended to recite the organic electronic device comprising the heat sink. No new matter is introduced. Claims 2 and 4-8 have been amended to provide proper dependency from Claim 1.

Claim 9 has been amended to recite the organic electronic device comprising the heat sink. No new matter is introduced. Claims 10 and 12-16 have been amended to provide proper dependency from Claim 9.

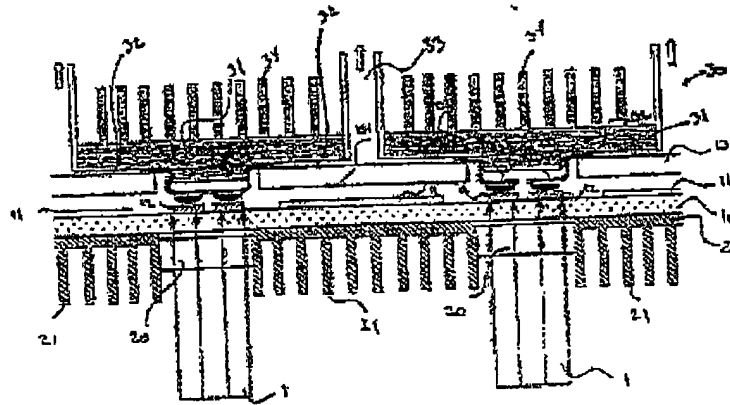
Rejections under 35 U.S.C. § 103(a): Claims 1, 2, 4, 5, 7, 9, 10 and 12-15

Claims 1, 2, 4, 5, 7, 9, 10 and 12-15 were rejected under 35 U.S.C. § 103(a) as obvious over U.S. Patent Application No. 2001/00482234 ("*Liu*"). Applicants respectfully traverse the rejection of amended Claim 1 for the reason that *Liu* neither teaches nor suggests an organic electronic device comprising a heat sink wherein the heat sink has a side with a pattern that extends at least partially through a thickness of the heat sink, the heat sink has a thickness no greater than 9 mm and the heat sink is attached to an array within the organic electronic device.

In particular, FIG. 1 of *Liu* (reproduced below) is a schematic view of a *sealing assembly* for an OLED 11 and not a view of an organic electronic device. It shows the fins (heat sinks) 34 that are part of the base assembly 31 and the heat sink 21 that is part of the chuck assembly 20. Both the base assembly 31 and the chuck assembly 20 are part of the *sealing assembly* and not the OLED 11. See *Liu* at paragraphs [0044] and [0045]. After the sealing process, the sealing assembly is removed and the base assembly 31 with fins (heat sinks) 34 and the chuck assembly 20 with heat sink 21 are removed. The fins (heat sinks) 34 and the heat sink 21 are not part of the OLED device. See *Liu* FIG. 11 and at paragraph [0041]. The heat sink of *Liu* is used in the manufacturing process during sealing of an OLED device, but is not itself part of the OLED device.

Application No.: 10/683,829
Docket No.: UC0343USCIP

Page 5

FIG.1 of *Liu*.

Because the heat sinks recited in *Liu* do not teach or suggest the elements of the invention claimed in pending Claims 1, 2, 4, 5, 7, 9, 10 and 12-15, there is no motivation to use a heat sink having the specifically claimed limitations without the benefit of hindsight after reviewing Applicants pending application. Applicants request the Examiner to withdraw the above referenced rejection.

Rejection under 35 U.S.C. § 103; Claims 6, 8 and 16

Claims 6, 8 and 16 were rejected under 35 U.S.C. § 103(a) as obvious over *Liu* in view of U.S. Patent No. 5,800,905 ("*Sheridan*").

For the reasons stated above, Applicants respectfully suggest that *Liu* does not teach the organic electronic device comprising a heat sink as claimed in pending Claims 6, 8 and 16. In particular, Claims 6 and 8 ultimately depend from amended Claim 1, which recites an organic electronic device comprising a heat sink wherein the heat sink has a patterned surface and a thickness no greater than 9mm and which is attached to an array within an organic electronic device. In addition, Claim 16 depends on Claim 10, which depends from amended Claim 9 that recites an organic electronic device comprising a heat sink wherein the heat sink has a ratio of area:thickness, as seen from a plan view, of at least 500:1 when the area and thickness are expressed in units of mm² and mm, respectively, and which is attached to an array within the organic electronic device. *Sheridan* does not make up the deficiencies of *Liu* in that it does not teach or suggest the elements missing from *Liu* and does not teach or suggest an organic electronic device comprising a heat sink wherein the heat sink has a side with a pattern that extends at least partially through a thickness of the heat sink, the side with the pattern has a black surface or wherein the side with the pattern is black.

Application No.: 10/683,829
Docket No.: UC0343USCIP

Page 6

Rather, *Sheridan* teaches "a pad including thermal insulation and heat sink areas whereby the pad can be used as a heat reflecting shield as well as a heat sink for dissipating heat at a desired location." See *Sheridan* at col. 2 lines 26-29. And, that the pad can include a plurality of layers and "at least one of the layers of the pad can include heat radiating means thereon. The heat radiating means can comprise a black surface on at least part of at least one side of at least one of the layers." (*Sheridan* col. 3 lines 17-20). It further states that "to dissipate heat from the pad, the heat radiating means such as a black surface can be provided on one or more portions of the pad located away from the site which is to be shielded from the heat" and "the black surface coating can be provided [sic] which will facilitate removing the heat to the heat sink area or heat sink areas." See *Sheridan* at col. 3 lines 27-30 and lines 34-37. Based on the foregoing, there is no teaching or suggestion to combine the heat sink of *Liu* with the multi-layer pad having a black surface to achieve the invention of pending Claims 6, 8 and 16. Moreover, there is no motivation to achieve the invention of the pending claims without the benefit of hindsight after reviewing the pending application.

Consequently, neither *Liu* or *Sheridan*, when read alone or together, teach or suggest the subject matter of amended pending Claims 6, 8 and 16. Thus, the above referenced rejection should be withdrawn.

Conclusion

In view of the foregoing, it is respectfully submitted that the application is in condition for allowance. A Notice of Allowance of the pending claims is earnestly requested.

Respectfully submitted,


MARY ANN CAPRIA
ATTORNEY FOR APPLICANT
Registration No.: 32,659
Telephone: (302) 992-3749
Facsimile: (302) 892-7949

Dated: 12.27.2005